

# SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

MARCH 1974 — REVISED MARCH 1988

- Gated Serial Inputs
- Fully Buffered Clock and Serial Inputs
- Asynchronous Clear

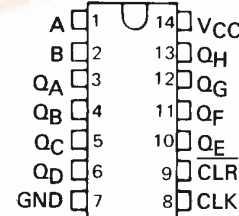
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'164	36 MHz	21 mW per bit
'LS164	36 MHz	10 mW per bit

## description

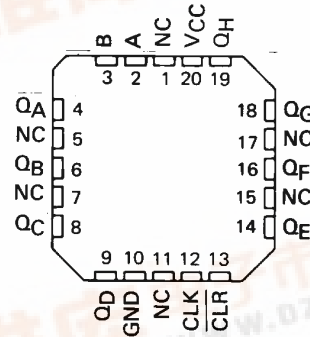
These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the low-to-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74164 and SN74LS164 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54164, SN54LS164 . . . J OR W PACKAGE  
SN74164 . . . N PACKAGE  
SN74LS164 . . . D OR N PACKAGE  
(TOP VIEW)



SN54LS164 . . . FK PACKAGE  
(TOP VIEW)



NC — No internal connection

FUNCTION TABLE

INPUTS				OUTPUTS			
CLEAR	CLOCK	A	B	QA	QB	...	QH
L	X	X	X	L	L	...	L
H	L	X	X	QA0	QB0	...	QH0
H	↑	H	H	H	QA <sub>n</sub>	...	QH <sub>n</sub>
H	↑	L	X	L	QA <sub>n</sub>	...	QH <sub>n</sub>
H	↑	X	L	L	QA <sub>n</sub>	...	QH <sub>n</sub>

H = high level (steady state), L = low level (steady state)

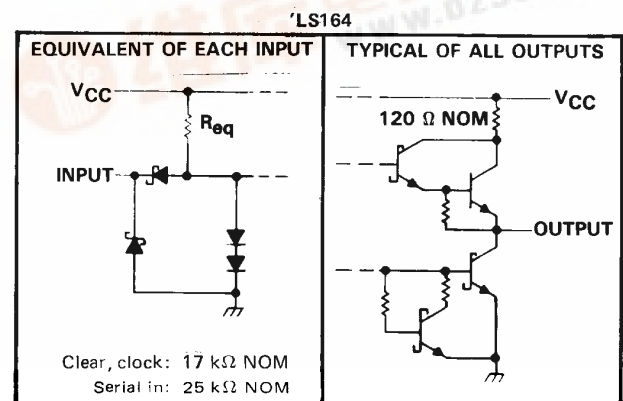
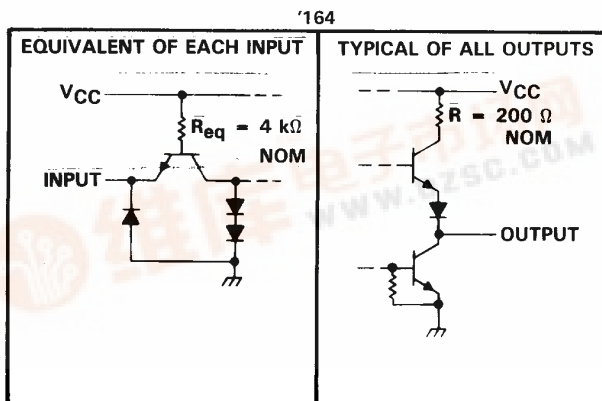
X = irrelevant (any input, including transitions)

↑ = transition from low to high level.

QA0, QB0, QH0 = the level of QA, QB, or QH, respectively, before the indicated steady-state input conditions were established.

QA<sub>n</sub>, QH<sub>n</sub> = the level of QA or QH before the most-recent ↑ transition of the clock; indicates a one-bit shift.

## schematics of inputs and outputs

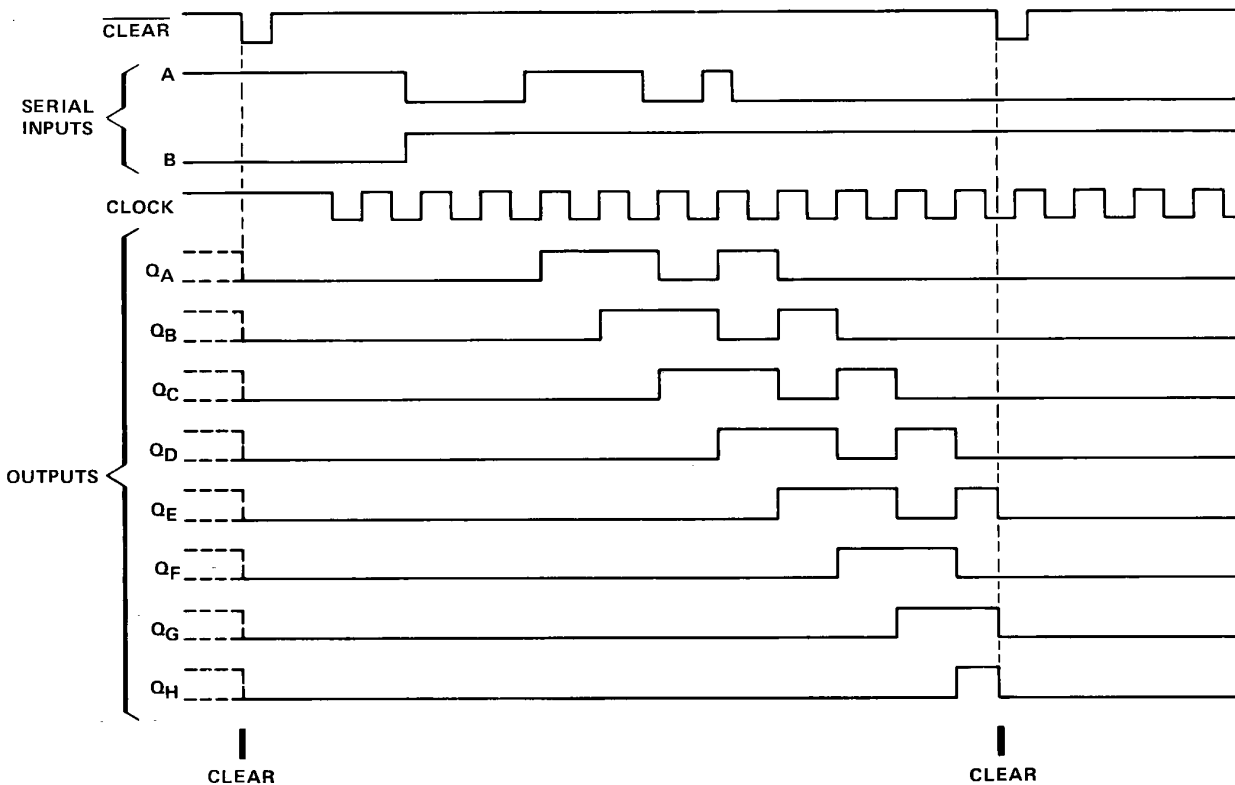


2

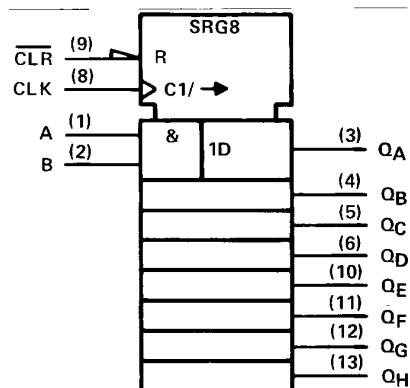
TTL Devices

## SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

typical clear, shift, and clear sequences



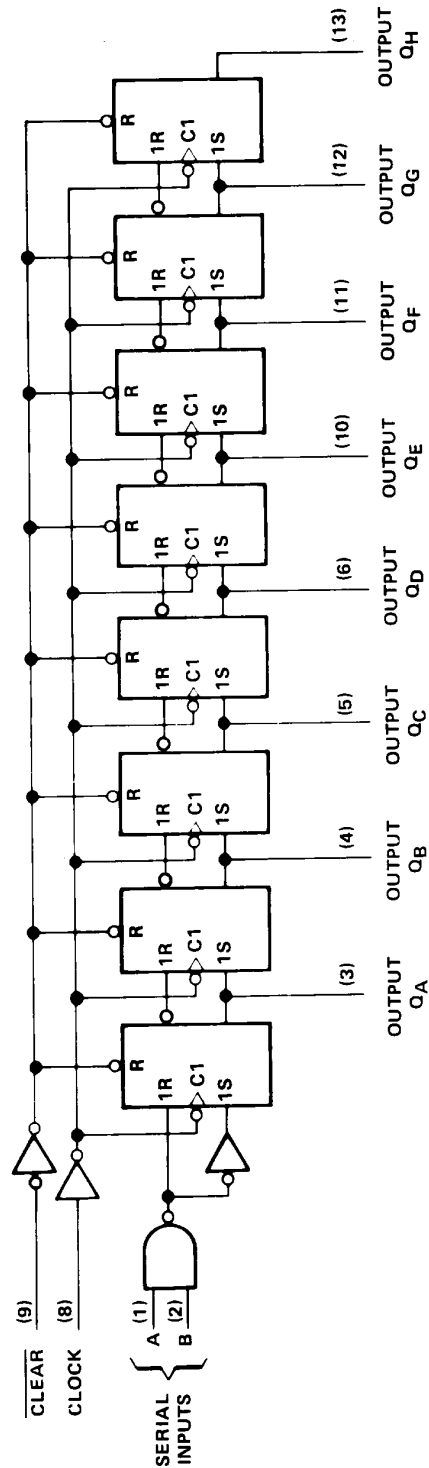
logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

**SN54164, SN54LS164, SN74164, SN74LS164**  
**8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS**

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

## SN54164, SN74164

### 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54164	–55°C to 125°C
SN74164	0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

	SN54164			SN74164			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, $V_{CC}$	4.5	5	5.5	4.75	5	5.25	V
High-level output current, $I_{OH}$			–400			–400	$\mu$ A
Low-level output current, $I_{OL}$			8			8	mA
Clock frequency, $f_{clock}$	0		25	0		25	MHz
Width of clock or clear input pulse, $t_W$	20			20			ns
Data setup time, $t_{SU}$ (see Figure 1)	15			15			ns
Data setup time, $t_{SU}$ (Clear Inactive) (see Figure 1)	20			20			ns
Data hold time, $t_H$ (see Figure 1)	5			5			ns
Operating free-air temperature, $T_A$	–55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54164			SN74164			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IH}$ High-level input voltage		2			2			V
$V_{IL}$ Low-level input voltage				0.8			0.8	V
$V_{IK}$ Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -12 \text{ mA}$			–1.5			–1.5	V
$V_{OH}$ High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -400 \mu\text{A}$	2.4	3.2		2.4	3.2		V
$V_{OL}$ Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 8 \text{ mA}$		0.2	0.4		0.2	0.4	V
$I_I$ Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$			1			1	mA
$I_{IH}$ High-level input current	$V_{CC} = \text{MAX}, V_I = 2.4 \text{ V}$			40			40	$\mu$ A
$I_{IL}$ Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			–1.6			–1.6	mA
$I_{OS}$ Short-circuit output current§	$V_{CC} = \text{MAX}$	–10		–27.5	–9		–27.5	mA
$I_{CC}$ Supply current	$V_{CC} = \text{MAX}, V_I(\text{clock}) = 0.4 \text{ V}$		30			30		mA
	See Note 2, $V_I(\text{clock}) = 2.4 \text{ V}$		37	54		37	54	

† For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ .

§ Not more than two outputs should be shorted at a time.

NOTE 2:  $I_{CC}$  is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

#### switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{max}$ Maximum clock frequency	$C_L = 15 \text{ pF}$	25	36		MHz
$t_{PHL}$ Propagation delay time, high-to-low-level Q outputs from clear input	$C_L = 15 \text{ pF}$		24	36	ns
	$C_L = 50 \text{ pF}$		28	42	
$t_{PLH}$ Propagation delay time, low-to-high-level Q outputs from clock input	$C_L = 15 \text{ pF}$	8	17	27	ns
	$C_L = 50 \text{ pF}$	10	20	30	
$t_{PHL}$ Propagation delay time, high-to-low-level Q outputs from the clock input	$C_L = 15 \text{ pF}$	10	21	32	ns
	$C_L = 50 \text{ pF}$	10	25	37	

# SN54LS164, SN74LS164

## 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS164	–55°C to 125°C
SN74LS164	0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

### recommended operating conditions

		SN54LS164			SN74LS164			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.7			0.8	V
$I_{OH}$	High-level output current			–0.4			–0.4	mA
$I_{OL}$	Low-level output current			4			8	mA
$f_{clock}$	Clock frequency	0		25	0		25	MHz
$t_w$	Width of clock or clear input pulse	20			20			ns
$t_{su}$	Data setup time (See Figure 1)	15			15			ns
$t_{su}$	Clear inactive setup time (See Figure 1)	20			20			ns
$t_h$	Data hold time (See Figure 1)	5			5			ns
$T_A$	Operating free-air temperature	–55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS164			SN74LS164			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			–1.5			–1.5	V
$V_{OH}$	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OH} = -0.4 \text{ mA}$	2.5	3.5		2.7	3.5		V
$V_{OL}$	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
	$I_{OL} = 8 \text{ mA}$					0.35	0.5	
$I_I$	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.1			0.1	mA
$I_{IH}$	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$		20			20		µA
$I_{IL}$	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			–0.4			–0.4	mA
$I_{OS}$	$V_{CC} = \text{MAX}$	–20		–100	–20		–100	mA
$I_{CC}$	$V_{CC} = \text{MAX}, \text{ See Note 3}$		16	27		16	27	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ .

§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 3:  $I_{CC}$  is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

### switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

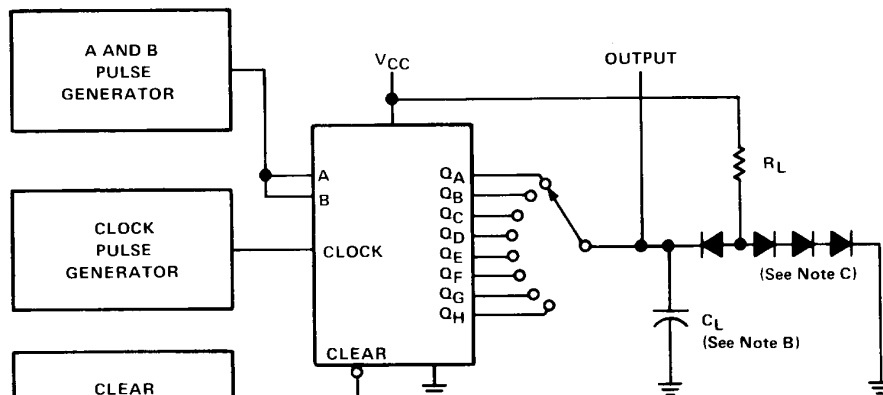
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{max}$ Maximum clock frequency		25	36		MHz
$t_{PHL}$ Propagation delay time, high-to-low-level Q outputs from clear input	$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF},$		24	36	ns
$t_{PLH}$ Propagation delay time, low-to-high-level Q outputs from clock input	See Figure 1		17	27	ns
$t_{PHL}$ Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns

2

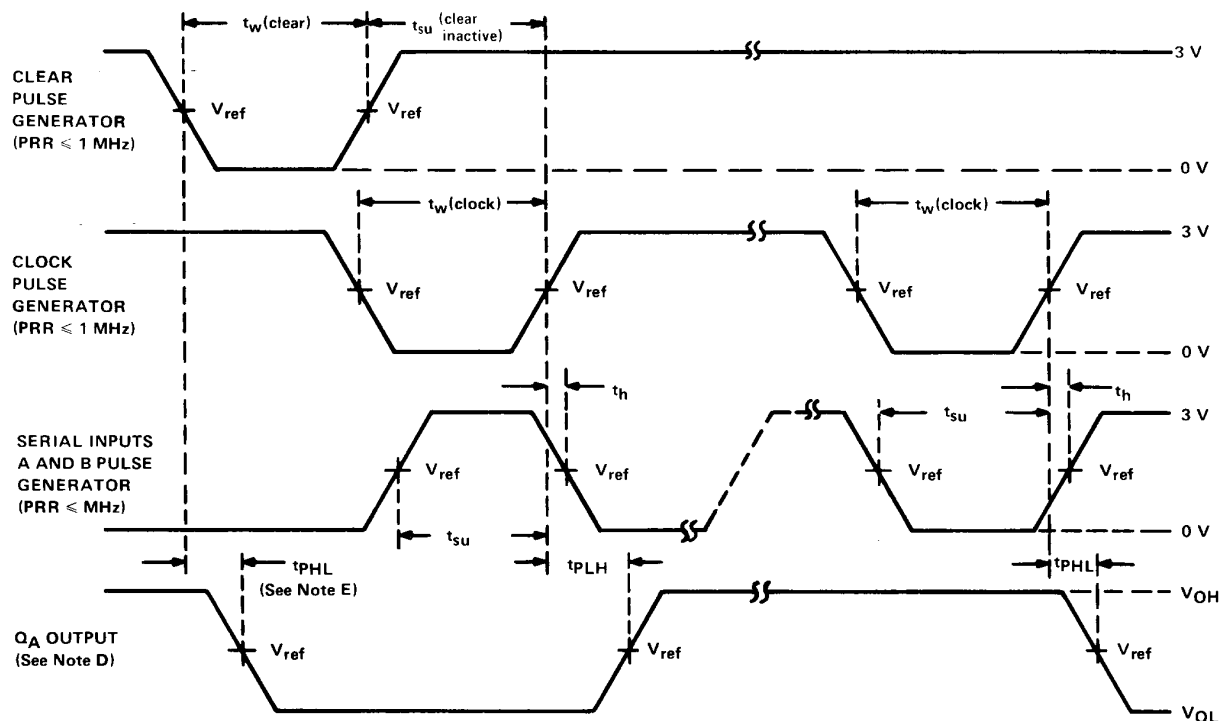
TTL Devices

# **SN54164, SN54LS164, SN74164, SN74LS164** **8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS**

## **PARAMETER MEASUREMENT INFORMATION**



**TEST CIRCUIT**



**VOLTAGE WAVEFORMS**

- NOTES: A. The pulse generators have the following characteristics: duty cycle  $\leq 50\%$ ,  $Z_{out} \approx 50 \Omega$ ; for '164,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns; and for 'LS164,  $t_r \leq 15$  ns,  $t_f \leq 6$  ns.
- B.  $C_L$  includes probe and jig capacitance.
- C. All diodes are 1N3064 or equivalent.
- D.  $Q_A$  output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
- E. Outputs are set to the high level prior to the measurement of  $t_{PHL}$  from the clear input.
- F. For '164,  $V_{ref} = 1.5$  V; for 'LS164,  $V_{ref} = 1.3$  V.

**FIGURE 1—SWITCHING TIMES**

2

TTL Devices

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/00903BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

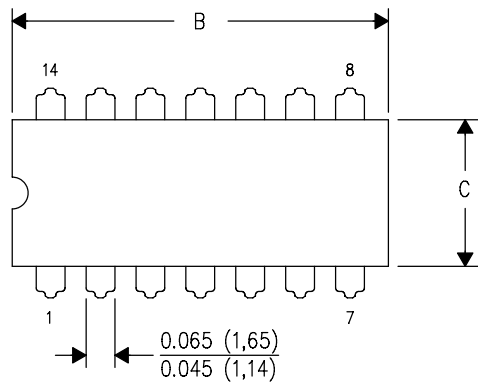
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



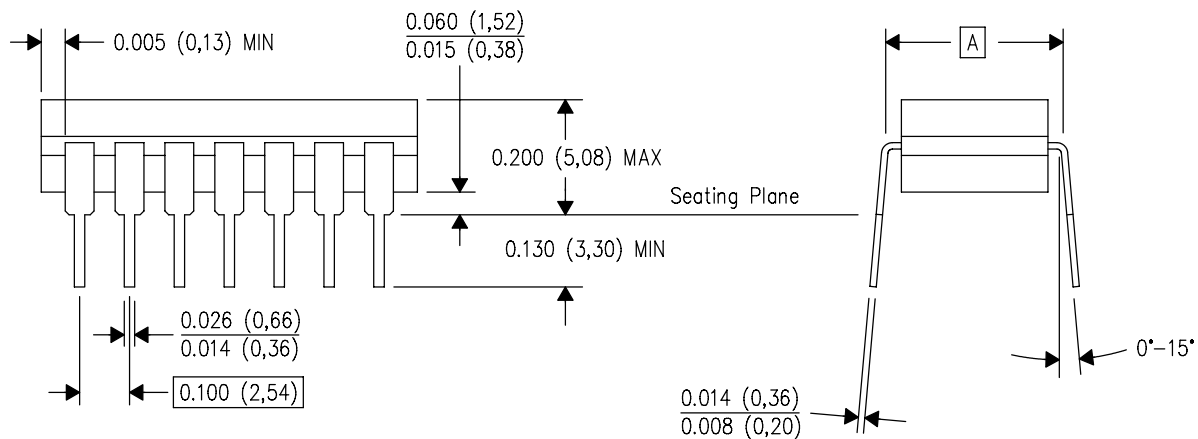
J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



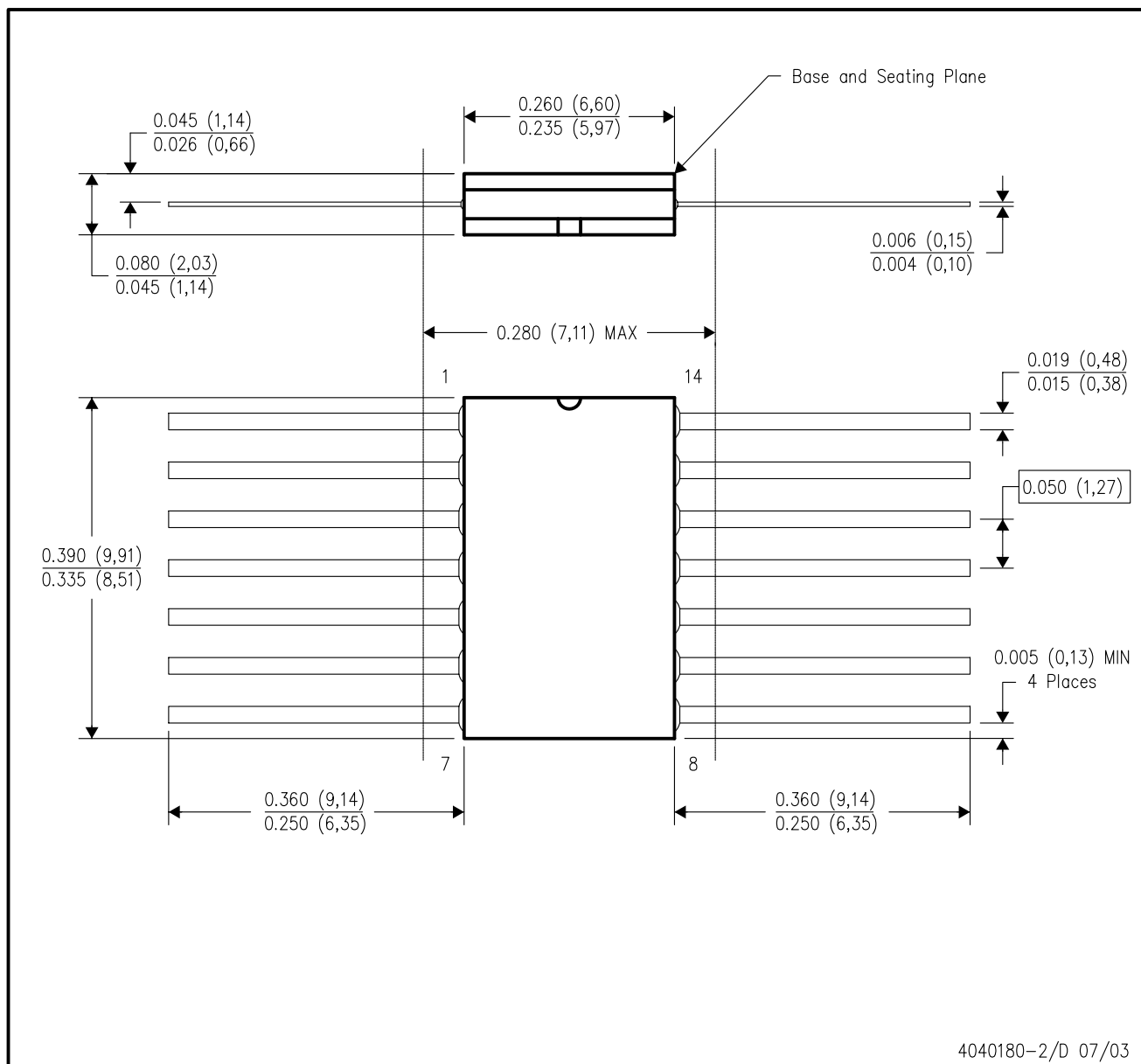
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



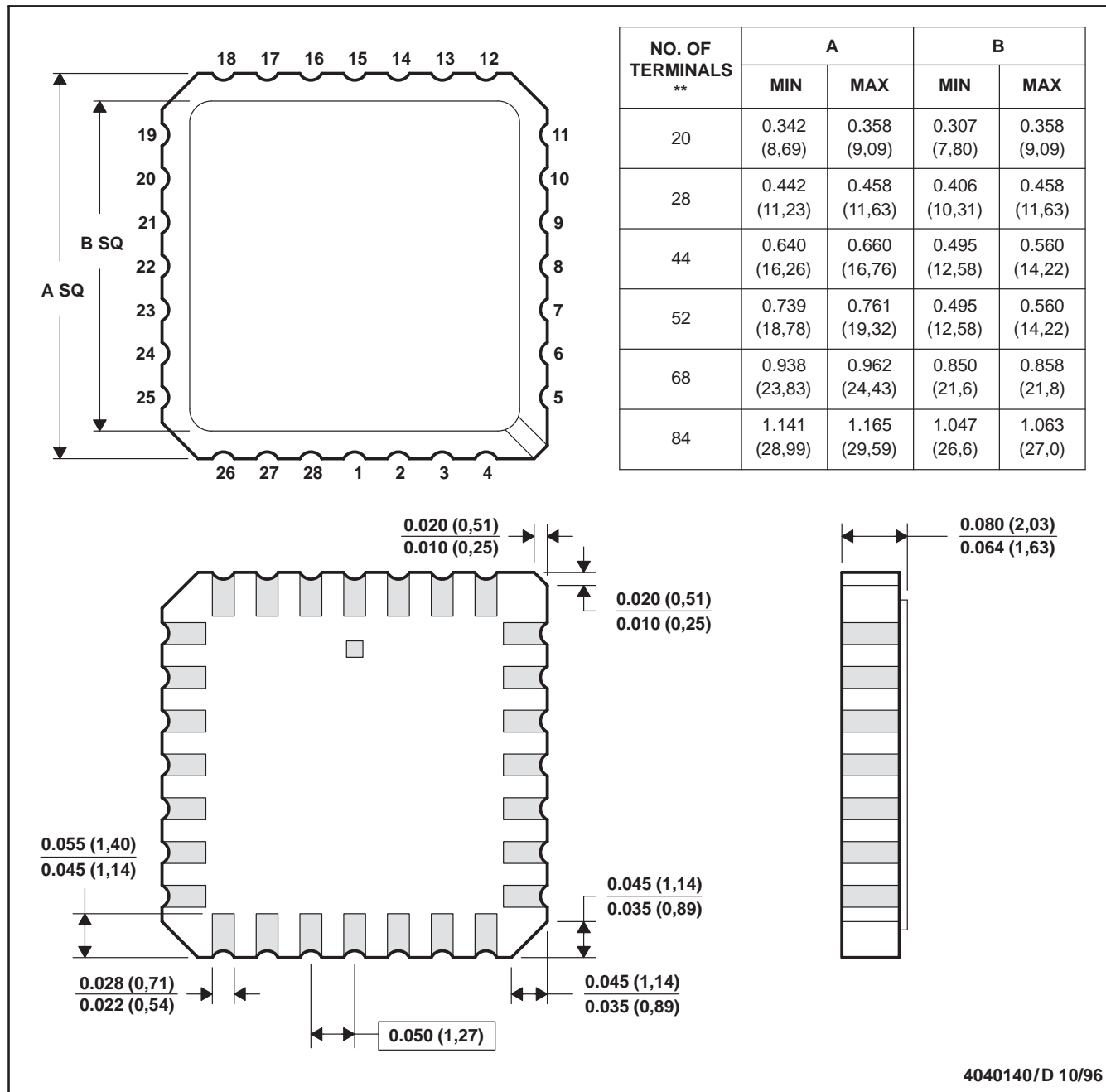
# MECHANICAL DATA

MLCC006B – OCTOBER 1996

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



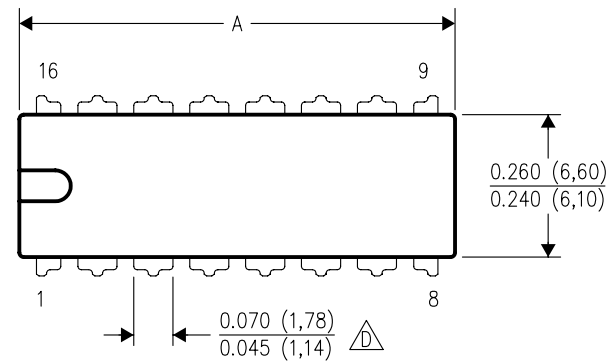
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

## MECHANICAL DATA

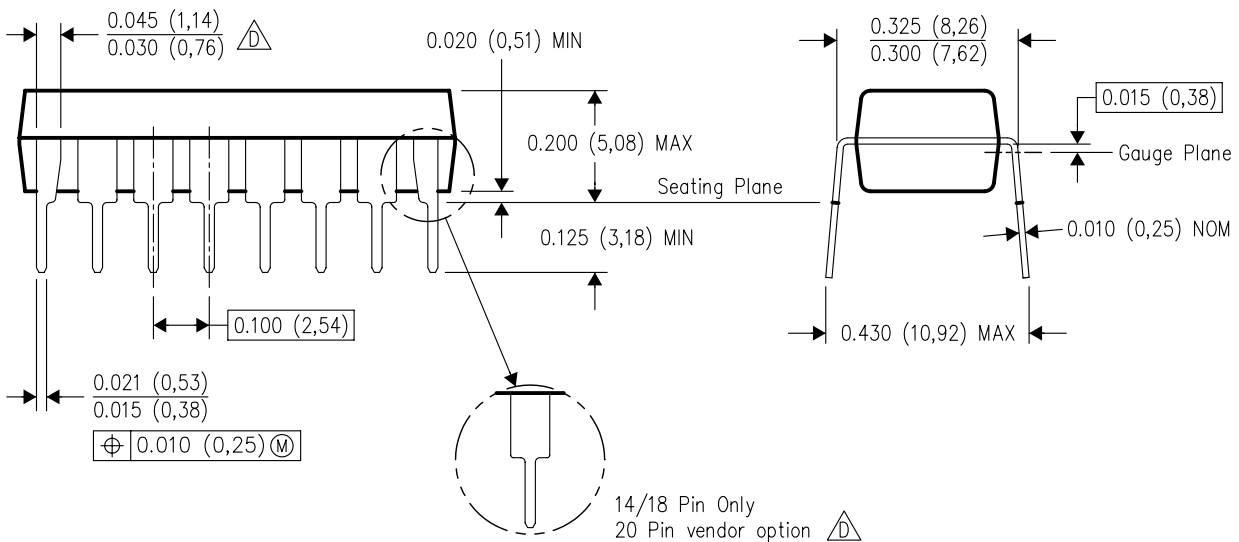
N (R-PDIP-T\*\*)

16 PINS SHOWN

# PLASTIC DUAL-IN-LINE PACKAGE





DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

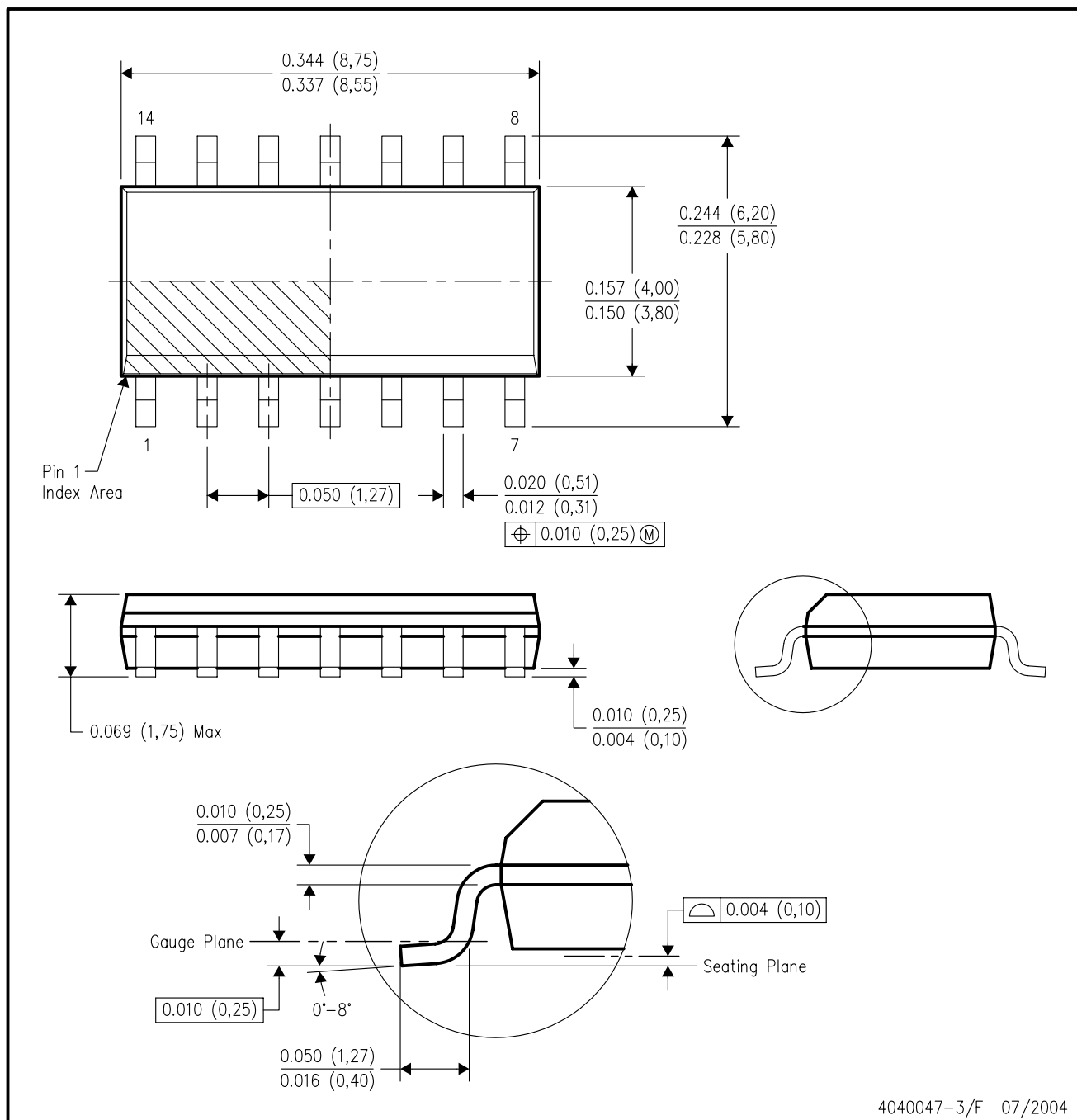
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
-  The 20 pin end lead shoulder width is a vendor option, either half or full width.

# MECHANICAL DATA

## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

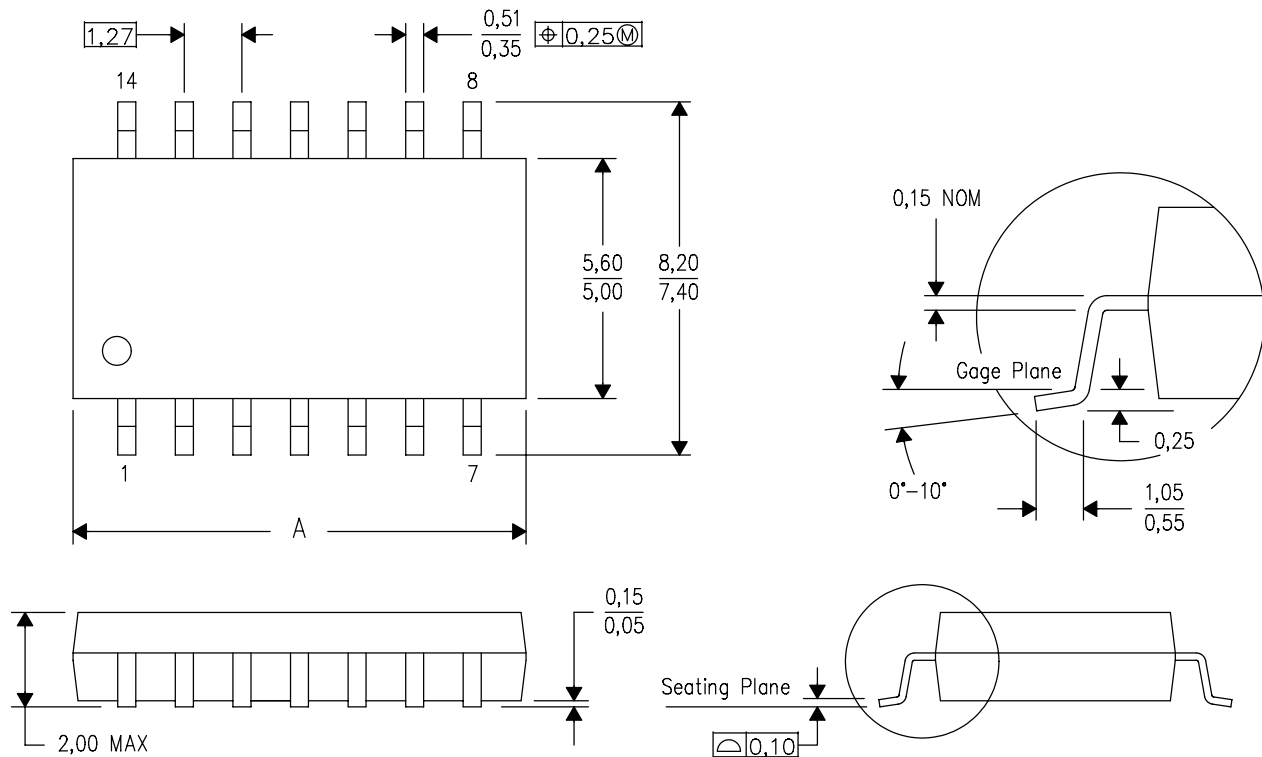
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AB.

## MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
		Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
		Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments  
Post Office Box 655303 Dallas, Texas 75265